



Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

1-59. (Canceled)

60. (Currently Amended) A method of manufacturing a wiring substrate, comprising:

disposing first and second droplets over a substrate, the first and second droplets not being in contact with each other, each of the first and second droplets including a first solvent component and a first functional particle;

gasifying a first part of the first solvent component from each of the first and second droplets by irradiating the first and second droplets with a first light to form first and second applied films over the substrate, the first and second applied films not being in contact with each other, each of the first and second applied films including a second part of the first solvent component and the first functional particle;

disposing a third droplet between the first and second applied films, the third droplet contacting at least one of the first and second applied films, the third droplet including a second solvent component and a second functional particle;

gasifying a first part of the second solvent component from the third droplet by irradiating the third droplet with the first light to form a third applied film between the first and second applied films, the third applied film contacting at least one of the first and second applied films, the third applied film including a second part of the second solvent component and the second functional particle; and

~~heating the first, second, and third applied films to exclude the excluding the~~
second part of the first solvent component and the second part of the second solvent

component from the first, second and third applied films by sintering the first, second and third applied films to form a functional material.

61. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, the process of ~~heating~~ sintering the first, second, and third applied films including irradiating the first, second, and third applied films with a second light, an intensity of the second light being higher than that of the first light.

62. (Currently Amended) The method of manufacturing a wiring substrate according to claim 60, each of the first and second applied films including a coating film that coats the first functional particle, the coating film being removed at the process of ~~heating~~ sintering the first, second, and third applied films.

63. (Previously Presented) The method of manufacturing a wiring substrate according to claim 60, the first and second droplets being discharged by a first head of an inkjet apparatus.

64. (Previously Presented) The method of manufacturing a wiring substrate according to claim 60, the first and second droplets being discharged by a first head of an inkjet apparatus, the third droplet being discharged by a second head of an inkjet apparatus.

65. (Previously Presented) The method of manufacturing a wiring substrate according to claim 60, the first light being a wide beam that is correspondingly beamed to the first and second droplets.

66. (Previously Presented) The method of manufacturing a wiring substrate according to claim 60, the first light being beamed to the first and the second droplets through a diffraction optical element.

67. (Previously Presented) The method of manufacturing a wiring substrate according to claim 60, the first light being reflected by a reflector before the first light is beamed to the first and second droplets.

68. (Previously Presented) The method of manufacturing a wiring substrate according to claim 60, the substrate being made of a transparent material, the first light passing from a second surface of the substrate to a first surface of the substrate, the first and the second droplets being disposed over the first surface of the substrate.

69. (Previously Presented) The method of manufacturing a wiring substrate according to claim 60, a viscosity of the first droplet being lower than that of the first applied film.

70. (Previously Presented) The method for manufacturing a wiring substrate according to claim 60, each of the first and second droplets including a photothermal conversion material that has an absorption band in the wavelength region of the first light.

71. (Currently Amended) A method of manufacturing a wiring substrate, comprising:

disposing a first droplet over a substrate, the first droplet including a first solvent component and a first functional particle;

gasifying a first part of the first solvent component from the first droplet by irradiating the first droplet with a first light to form a first applied film over the substrate, the first applied film including a second part of the first solvent component and the first functional particle;

disposing a second droplet over the substrate, the second droplet contacting at least a part of the first applied film, the second droplet including a second solvent component and a second functional particle;

gasifying a first part of the second solvent component from the second droplet by irradiating the second droplet with the first light to form a second applied film over the substrate, the second applied film contacting at least a part of the first applied film, the second

applied film including a second part of the second solvent component and the second functional particle;

~~heating the first and second applied films to exclude the~~excluding the second
part of the first solvent component and the second part of the second solvent component from
the first and second applied films by sintering the first and second applied films to form a
functional material.

72. (Currently Amended) The method of manufacturing a wiring substrate according to claim 71, the process of ~~sintering~~heating the first and second applied films including irradiating the first and second applied films with a second light, an intensity of the second light being higher than that of the first light.